

Application No.:  
10/523,494

Attorney Docket No.:  
Chelix-0008USAACN37

IN THE CLAIMS

1. (Withdrawn) A method to expose a conductive coating on an inner surface of a substrate in a flexible glazing structures including a pair of substrates, comprising offsetting the substrates such that the conductive coatings on at least one inner surfaces is exposed during and after curing.
2. (Previously Presented) A method of cutting flexible glazing structures comprising:  
applying a non-conductive barrier material to a first of a pair of substrates to be laminated before coating with liquid crystal material;  
laminating the pair of substrates with liquid crystal material therebetween; and  
cutting the laminate along the barrier lines.
3. (Original) A method to expose electrical contacts in flexible glazing structures comprising:  
cutting notches in both of a pair of substrates to be laminated;  
registering the substrates such that the notches do not overlap when the substrates are laminated together.
4. (Previously Presented) A method of cutting flexible glazing structures as in claim 2 further comprising:  
shearing the first substrate to expose the second substrate along one edge of cut shape;  
and  
shearing the second substrate to expose the first substrate along another edge of cut shape.
5. (Previously Presented) A method of cutting flexible glazing structures comprising:  
laminating a pair of substrates having liquid crystal material therebetween;

Application No.:  
10/523,494

Attorney Docket No.:  
Chelix-0008USAAACN37

lowering the temperature of the substrates and liquid crystal material to a temperature sufficiently low to increase the viscosity of the liquid crystal material; and

cutting the laminate, whereby due to the high viscosity, the substrates do not contact one another.

6. (Previously Presented) A method of forming shaped glazing structures comprising:  
applying barrier material to a first substrate for defining a shape;  
coating liquid crystal material on the first or a second substrate;  
cutting the first and second substrates;  
laminating the cut substrates together;  
shearing a portion of one of the substrates to expose an area of an inner conductive coating of the substrate; and  
curing the laminate.

7. (Canceled)

8. (Previously Presented) A method of forming shaped glazing structures as in claim 6, wherein coating is performed prior to cutting.

9. (Previously Presented) A method of forming shaped glazing structures as in claim 6, wherein cutting is performed prior to coating.